COMPONENTS MARKED ‘DNP’ SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

<table>
<thead>
<tr>
<th>PCB VIEWED FROM BOTTOM SIDE</th>
<th>BOARD #: TIDA-D1465</th>
<th>REV: E1</th>
<th>SUN REV: Not In VersionControl</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>IGNORE -&gt;</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

PLOT NAME = Bottom Assembly Drawing  GENERATED: 2017/8/4  21:42:54  TEXAS INSTRUMENTS
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